



Click [here](#) for the 3D model.

### Dimensions

Chip Size	1206
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	1.1mm +/-0.10mm
B	0.5mm +/-0.25mm

### Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	2500

### General Information

Series	SMD COTS COG
Style	SMD Chip
Description	SMD, MLCC, COTS, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
Failure Rate	Testing per MIL-PRF-55681 PDA 8%, DPA per EIA-469, Humidity per MIL-STD-202, Method 103, Condition A
AEC-Q200	No
Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	1000 pF
Measurement Condition	1MHz 1.0Vrms
Capacitance Tolerance	2%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MHz 1.0Vrms
Dissipation Factor	0.1% 1MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms